BAV99WT1, BAV99RWT1

Preferred Devices

Dual Series Switching Diodes

The BAV99WT1 is a smaller package, equivalent to the BAV99LT1.

Features

• Pb–Free Packages are Available

Suggested Applications

- ESD Protection
- Polarity Reversal Protection
- Data Line Protection
- Inductive Load Protection
- Steering Logic

MAXIMUM RATINGS (Each Diode)				
Rating	Symbol	Value	Unit	
Reverse Voltage	V _R	70	Vdc	
Forward Current	١ _F	215	mAdc	
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc	
Repetitive Peak Reverse Voltage	V _{RRM}	70	V	
Average Rectified Forward Current (Note 1) (averaged over any 20 ms period)	I _{F(AV)}	715	mA	
Repetitive Peak Forward Current	I _{FRM}	450	mA	
Non-Repetitive Peak Forward Current $t = 1.0 \ \mu s$ $t = 1.0 \ ms$ $t = 1.0 \ S$	I _{FSM}	2.0 1.0 0.5	A	

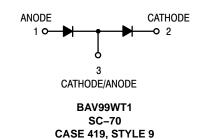
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

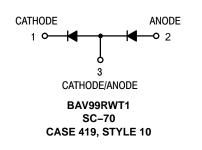
1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.



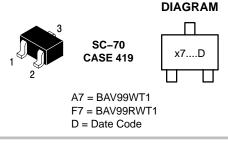
ON Semiconductor[®]

http://onsemi.com









ORDERING INFORMATION

Device	Package	Shipping [†]
BAV99WT1	SC-70	3000/Tape & Reel
BAV99WT1G	SC-70 (Pb-Free)	3000/Tape & Reel
BAV99RWT1	SC-70	3000/Tape & Reel
BAV99RWT1G	SC–70 (Pb–Free)	3000/Tape & Reel

⁺For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

BAV99WT1, BAV99RWT1

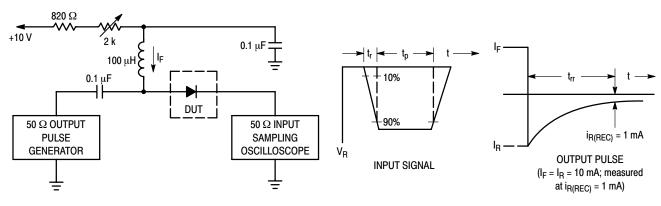
THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T _A = 25°C Derate above 25°C	P _D	200 1.6	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	625	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^{\circ}C$ Derate above $25^{\circ}C$	P _D	300 2.4	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{ hetaJA}$	417	°C/W
Junction and Storage Temperature	TJ, T _{stg}	-65 to +150	°C

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted) (Each Diode)

Characteristic		Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Breakdown Voltage ($I_{(BR)}$ = 100 μ A)	V _(BR)	70	-	Vdc
Reverse Voltage Leakage Current (V _R = 70 Vdc) (V _R = 25 Vdc, T _J = 150°C) (V _R = 70 Vdc, T _J = 150°C)	I _R		2.5 30 50	μAdc
Diode Capacitance ($V_R = 0, f = 1.0 \text{ MHz}$)	CD	-	1.5	pF
Forward Voltage $(I_F = 1.0 \text{ mAdc})$ $(I_F = 10 \text{ mAdc})$ $(I_F = 50 \text{ mAdc})$ $(I_F = 150 \text{ mAdc})$	VF	- - -	715 855 1000 1250	mVdc
Reverse Recovery Time (I_F = I_R = 10 mAdc, i_{R(REC)} = 1.0 mAdc) (Figure 1) R_L = 100 Ω	t _{rr}	_	6.0	ns
Forward Recovery Voltage (I _F = 10 mA, t_r = 20 ns)	V _{FR}	-	1.75	V

1. FR-5 = 1.0 \times 0.75 \times 0.062 in. 2. Alumina = 0.4 \times 0.3 \times 0.024 in. 99.5% alumina.



Notes: (a) A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA. (b) Input pulse is adjusted so I_{R(peak)} is equal to 10 mA. (c) t_p » t_{rr}



BAV99WT1, BAV99RWT1

CURVES APPLICABLE TO EACH DIODE

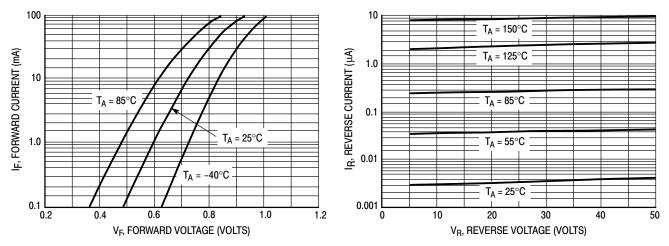


Figure 2. Forward Voltage

Figure 3. Leakage Current

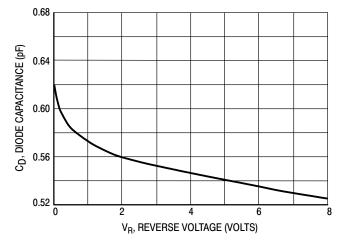
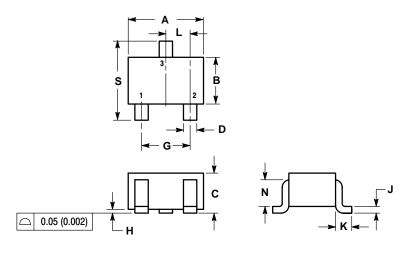


Figure 4. Capacitance

PACKAGE DIMENSIONS

SC-70 (SOT-323) CASE 419-04 ISSUE L



NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2.	CONTROLLING DIMENSION: INCH.	

	INCHES		MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
С	0.032	0.040	0.80	1.00	
D	0.012	0.016	0.30	0.40	
G	0.047	0.055	1.20	1.40	
Н	0.000	0.004	0.00	0.10	
J	0.004	0.010	0.10	0.25	
K	0.017 REF		0.425 REF		
L	0.026 BSC 0.028 REF		0.650 BSC 0.700 REF		
Ν					
S	0.079	0.095	2.00	2.40	

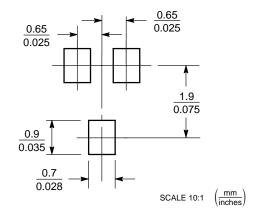
STYLE 9: PIN 1. ANODE

> 2. CATHODE 3. CATHODE-ANODE

STYLE 10: PIN 1. CATHODE 2. ANODE

3. ANODE-CATHODE

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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